Allen Baum

Biosketch:

Allen Baum is the incumbent TCMM chair and is running for re-election, for a second 2-year term.

Allen Baum has been associated with numerous IEEE-sponsored conferences as
- presenter (Compcon 1974, Asilomar Microcomputer Workshop 2000, 2013, Computer Elements Workshop 1995, 1997), IEEE ICCE (1998}
- program committee member (Compcon 1994-7, Hot Chips 1996, 2000),
- program committee co-chair (Hot Chips 1997, 2011),
- organizing committee member (ASPLOS 1991, Hot Chips 1998-2014) and
- organizing committee general chair (Hot Chips 1998)

He has been on the Hot Chips and Hot Interconnects steering committees since 1998.
He was also guest editor of IEEE Micro in April 1998, 2001, and 2012 for the Hot Chips issues.

Allen has 40 years of experience in processor design at Hewlett-Packard, Apple Computer, ARM, Digital Equipment/Compaq and Intel, and is currently working at a microprocessor startup. Earlier he worked on Intel's Quickpath interprocessor interconnect, RISC architecture development for Apple, ARM8 architecture at ARM for Apple, HP-45 firmware and part of the PA RISC architecture development team at Hewlett-Packard, and was architect of the Apple II I/O system and co-author of its monitor ROM. He holds 30 patents for innovations in microprocessor design. Allen received his B.S.E.E and M.S.E.E (1974) degrees in electrical engineering from M.I.T. He has been a member of the IEEE since 1970.

Position Statement:

I've worked on various IEEE conferences, especially Hot Chips, as general chair, program co-chair, and as a member of the program committee, organizing committee, and steering committee.

TCMM is unusual in that it sponsors several conferences that stress the overlap of industrial and academic work and viewpoints. (Most other conferences sponsored by IEEE are solely academic.) Hot Chips, for example, primarily presents talks on the architecture and implementation of real industrial products (including those shipping and those in development), with a stress on the interesting conceptual and design features.
I strongly support this direction for TCMM sponsored conferences, including Hot Chips, Hot Interconnects, and Cool Chips. And now Multi-Core Systems-on-Chip.

I'm committed to ensuring that TCMM conferences are financially stable, attract both great content and attendees, and I plan to explore synergies between them to reduce the effort, cost and workload of the volunteers that put them on, including easing the interface between conference committees and IEEE/.